



TRANSMITTAL OF FORMAL DRAWINGS

Docket No.
SLA0709

Application Of: Tingkai Li, Wei Pan, Robert A. Barrowcliff, David R. Evans and Sheng Teng Hsu

| Serial No. | Filing Date | Batch No. | Examiner | Art Unit |
|------------|-------------|-----------|----------------|----------|
| 10/621,863 | 07/16/2003 | | Hsien Ming Lee | 2823 |

Invention: MOCVD of TiO₂ Thin Film for Use as FeRAM H₂ Passivation Layer

Address to:
Assistant Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith are:

4 sheets of formal drawing(s) for this application.

Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c) on the reverse side of the drawing.

Signature

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Dated: December 23, 2004

I certify that this document and attached formal drawings are being deposited on December 23 2004 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

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